

Received  
10/03/2006

**SEMICONDUCTOR PACKAGE AND METHOD FOR MANUFACTURING THE  
SAME**

Appl. No. : 10/710,399 Confirmation No. 4398  
Applicant : Min-Jer Lin  
Filed : July 8, 2004  
TC/A.U. : 2818  
Examiner : DAO H. NGUYEN  
Docket No. : LKSP0027USA0  
Customer No. : 27765

Do Not Enter

Thanks,

DN

10/05/2006

Commissioner for Patents  
P.O. Box 1450  
Alexandria VA 22313-1450

**AMENDMENT**

5 Sir:

In response to the Office action of June 9, 2006, please amend the above-identified application as follows:

**Amendments to the Specification** begin on page 2 of this paper.

10 **Amendments to the Claims** are reflected in the listing of claims which begins on page 4 of this paper.

**Remarks/Arguments** begin on page 7 of this paper.